

SOT-23

/ Features

Small signal diode, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

High Conductance Ultra Fast Diode, Meet the stringent requirements of automotive applications.

/ Marking

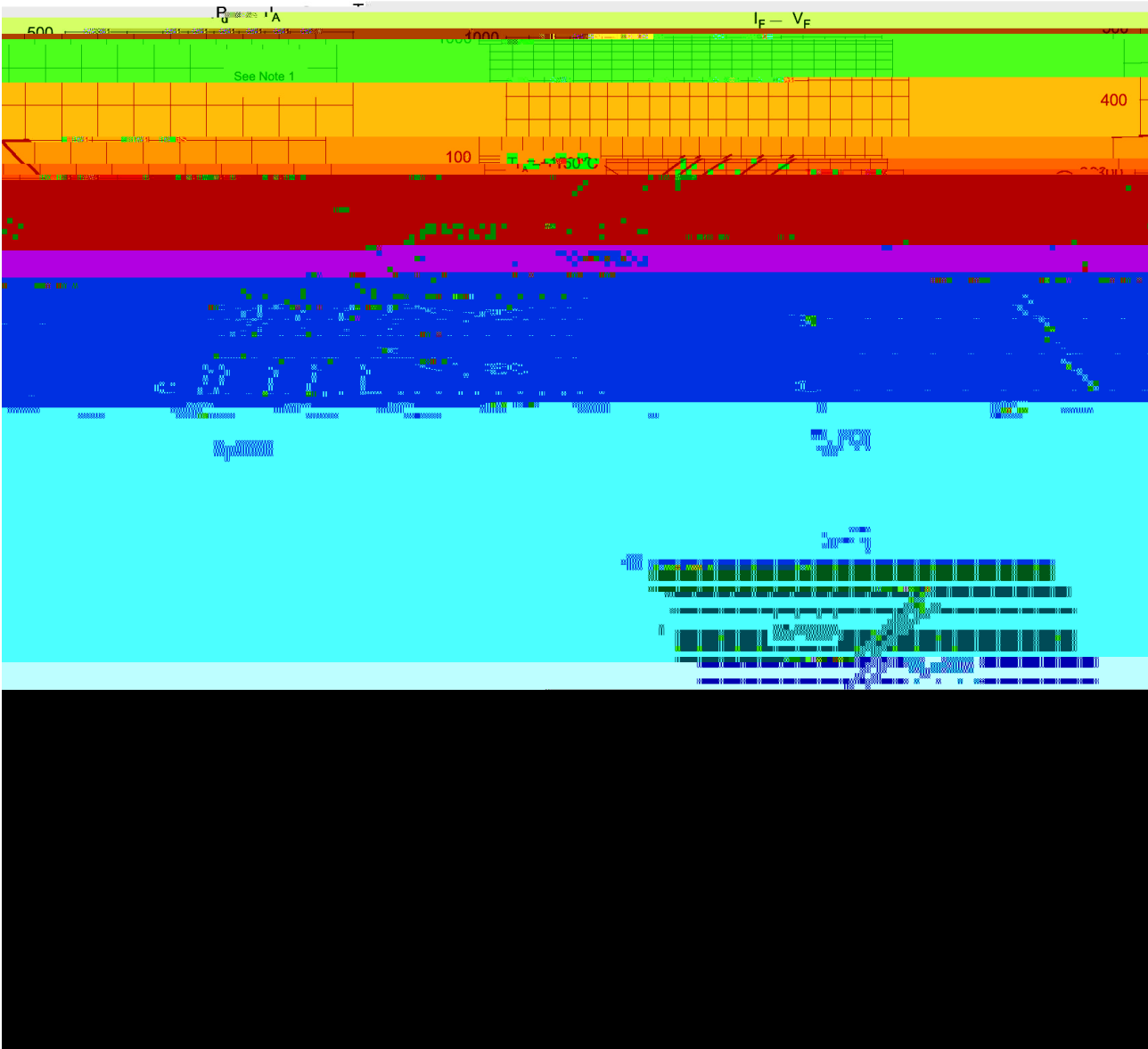
Marking	QA4
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Parameter	Symbol	Rating	Unit
Maximum Repetitive Reverse Voltage	V_{RRM}	75	V
Breakdown Voltage	V_R	70	V
Average Rectified Forward Current	$I_{F(AV)}$	200	mA
Non-repetitive Peak Forward Surge Current	$I_{FSM(1)}(\text{pulse width}=1.0S)$	1.0	A
	$I_{FSM(2)}(\text{pulse width}=1.0mS)$	2.0	A
Power Dissipation	P_D	350	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	357	/W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

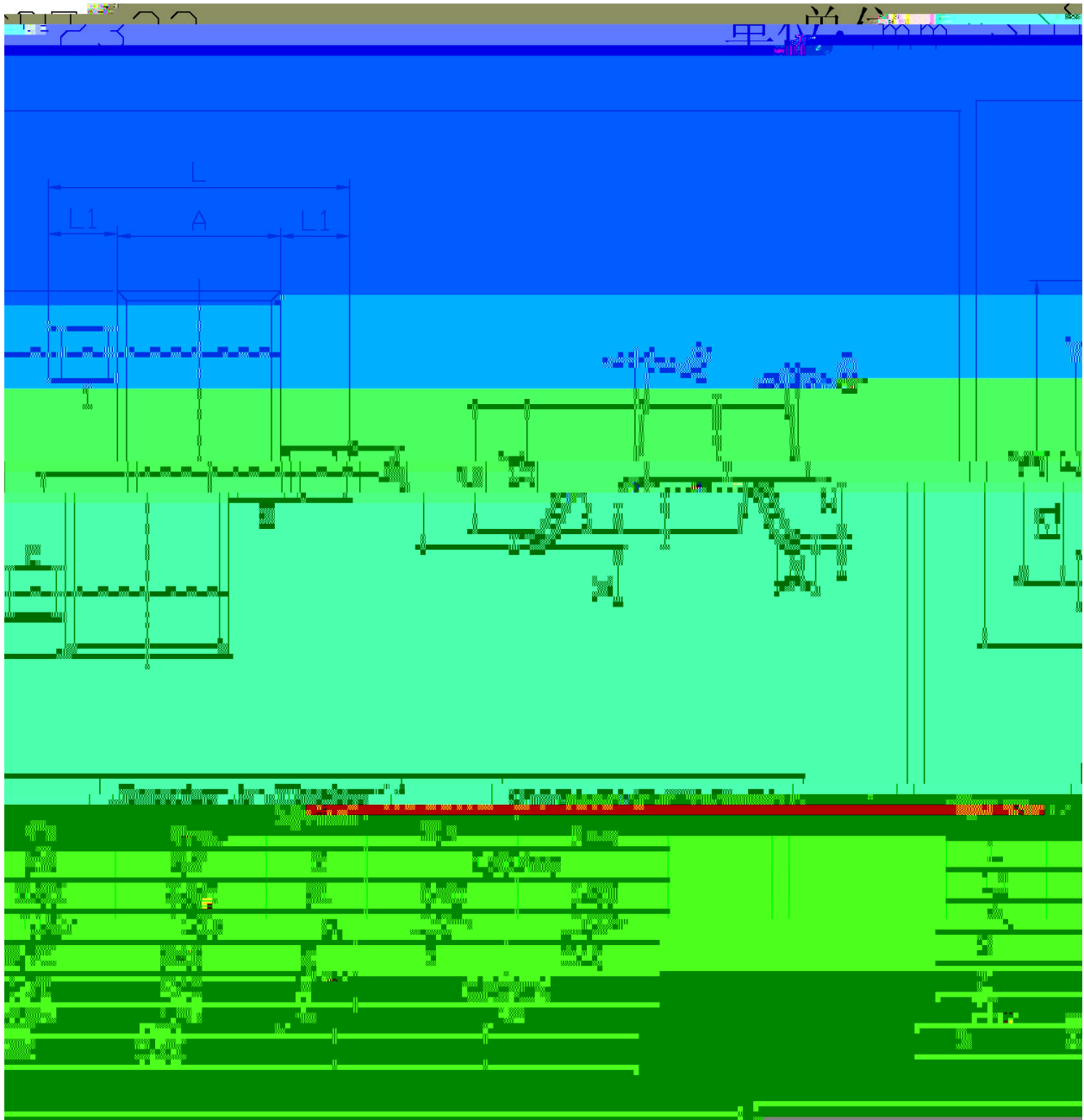
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Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Voltage	V_R	$I_R=100\mu A$	70			V
Forward Voltage	V_F	$I_F=1.0mA$			715	mV
		$I_F=10mA$			855	mV

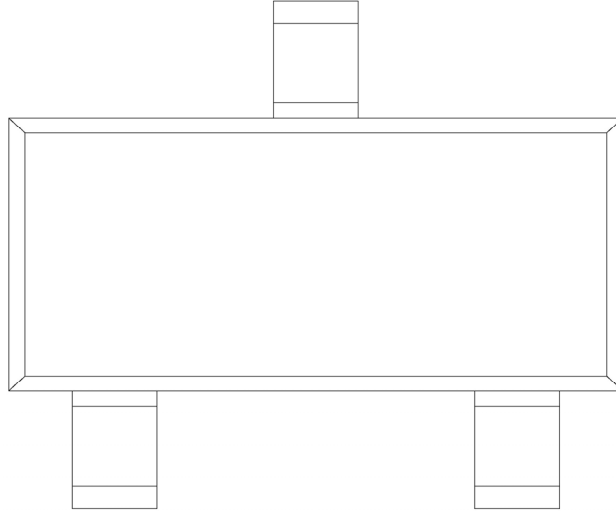
/ Electrical Characteristic Curve



/ Package Dimensions

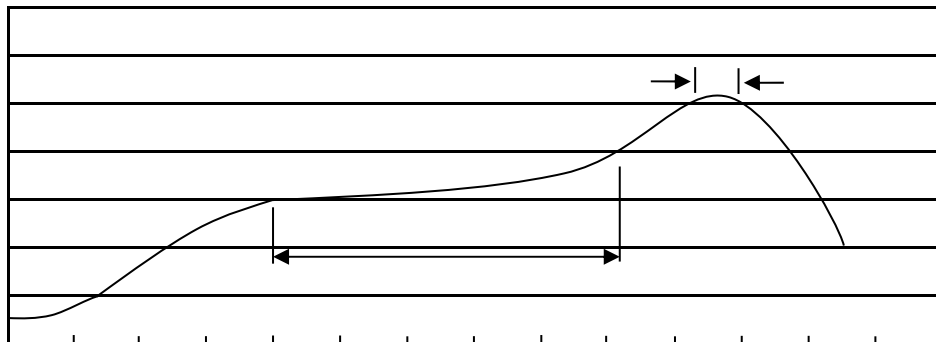


/ Marking Instructions



Q
A4

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--|
| 1 | 150 | 200 | 60 | 120sec; | 1.Preheating:150~200 , Time:60~120sec. |
| 2 | 255±5 | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 /sec. | 3.Cooling Speed: 2~10 /sec. | |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180000	7 ×8	180×120×180	390×385×205

/ Notices